

INTERNATIONAL STANDARD

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Test methods for electrical materials, printed board and other interconnection structures and assemblies –

Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –

Partie 5-503: Méthode d'essai générale pour les matériaux et les assemblages – Essais des filaments anodiques conducteurs (CAF) des cartes à circuits



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CONTENTS

| | |
|---|----|
| FOREWORD..... | 4 |
| 1 Scope..... | 6 |
| 2 Normative references | 6 |
| 3 Terms and definitions | 6 |
| 4 Testing condition | 7 |
| 4.1 Standard condition | 7 |
| 4.2 Judgment state | 8 |
| 5 Specimen | 8 |
| 5.1 Outline of CAF test vehicle design | 8 |
| 5.1.1 Evaluation design for the glass cloth direction | 8 |
| 5.1.2 Design between plated through hole (PTH)..... | 9 |
| 5.2 CAF test board..... | 10 |
| 5.2.1 Example A..... | 10 |
| 5.2.2 Example B..... | 11 |
| 5.3 Number of specimens | 13 |
| 6 Equipment/Apparatus or material..... | 13 |
| 6.1 Environmental test chamber..... | 13 |
| 6.2 Measuring equipment..... | 13 |
| 6.3 Power supply | 13 |
| 6.4 Current limiting resistors | 14 |
| 6.5 Connecting wire | 14 |
| 6.6 Other dedicated fixtures..... | 14 |
| 7 Resistance measurement method | 14 |
| 7.1 Manual insulation resistance measurement method | 14 |
| 7.2 Automatic insulation resistance measurement method | 15 |
| 8 Test method | 16 |
| 8.1 Test method selection | 16 |
| 8.2 Steady-state temperature and humidity test | 16 |
| 8.2.1 Object..... | 16 |
| 8.2.2 Test condition..... | 16 |
| 8.3 Temperature and humidity (12 h + 12 h) cycle test..... | 16 |
| 8.3.1 Object..... | 16 |
| 8.3.2 Test condition | 17 |
| 8.3.3 Number of cycles of the test | 17 |
| 8.4 Temperature and humidity cyclic test with and without low temperature exposure..... | 17 |
| 8.4.1 Object..... | 17 |
| 8.4.2 Test condition | 17 |
| 8.5 Steady-state high temperature and high humidity (unsaturated pressurized vapour) test | 17 |
| 8.5.1 Object..... | 17 |
| 8.5.2 Test condition | 18 |
| 9 Procedure..... | 18 |
| 9.1 Test specimen preparation..... | 18 |
| 9.1.1 General | 18 |
| 9.1.2 Sample identification | 18 |

| | | |
|-----------------------|--|----|
| 9.1.3 | Prescreen for opens and shorts | 18 |
| 9.1.4 | Cleaning | 19 |
| 9.1.5 | Connecting wire..... | 19 |
| 9.1.6 | Cleaning after attachment..... | 19 |
| 9.1.7 | Dry | 19 |
| 9.2 | Precondition..... | 19 |
| 9.3 | Test procedure..... | 19 |
| 9.3.1 | Setting of the specimen | 19 |
| 9.3.2 | Test voltage and measuring voltage | 19 |
| 9.3.3 | Temperature and humidity condition at the start time of the test | 20 |
| 9.3.4 | Measurement..... | 20 |
| 9.3.5 | Procedure in test interruption..... | 21 |
| 9.3.6 | End of test..... | 21 |
| 9.4 | Visual inspection..... | 21 |
| 9.4.1 | General | 21 |
| 9.4.2 | Shape of electrochemical migration | 21 |
| Annex A (informative) | Forms of electrochemical migration | 22 |
| A.1 | Example of dendrite-shaped migration | 22 |
| A.2 | CAF (Example of migration along the glass fibre)..... | 22 |
| Bibliography | | 23 |
| Figure 1 | – Schematic of in-line test comb, with possible failure site | 8 |
| Figure 2 | – Schematic of staggered test comb, with possible failure site | 9 |
| Figure 3 | – Manhattan distance..... | 9 |
| Figure 4 | – Schematic section of via pair with bias | 10 |
| Figure 5 | – Example of inner layer via pads and layer patterns | 10 |
| Figure 6 | – Example of no inner layer via pads and layer patterns..... | 10 |
| Figure 7 | – Insulation evaluation pattern for through-holes and via holes | 11 |
| Figure 8 | – Layouts of the two versions of the CAF test boards | 12 |
| Figure 9 | – Measurement with insulation resistance meter | 15 |
| Figure 10 | – Temperature and humidity in a test | 20 |
| Figure A.1 | – Example which is generated on the board surface | 22 |
| Figure A.2 | – Example of CAF..... | 22 |
| Table 1 | – Dimension of insulation evaluation pattern for through-holes | 11 |
| Table 2 | – Test structures A1 through A4 design rules | 12 |
| Table 3 | – Test structures B1 through B4 design rules | 13 |
| Table 4 | – Test condition..... | 16 |
| Table 5 | – Number of cycles of the test | 17 |
| Table 6 | – Test condition..... | 17 |
| Table 7 | – Test condition (IEC 60068-2-66)..... | 18 |

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 5-503: General test method for materials and assemblies –
Conductive anodic filaments (CAF) testing of circuit boards**

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International Standard IEC 61189-5-503 been prepared by IEC technical committee 91: Electronics assembly technology.

This bilingual version (2019-09) corresponds to the monolingual English version, published in 2017-05.

The text of this standard is based on the following documents:

| FDIS | Report on voting |
|--------------|------------------|
| 91/1433/FDIS | 91/1443/RVD |

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

The French version of this standard has not been voted upon.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

1 Scope

This part of IEC 61189 specifies the conductive anodic filament (hereafter referred to as CAF) and specifies not only the steady-state temperature and humidity test, but also a temperature-humidity cyclic test and an unsaturated pressurized vapour test (HAST).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:2013, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-30, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60068-2-38, *Environmental testing – Part 2-38: Tests – Test Z/AD: Composite temperature/humidity cyclic test*

IEC 60068-2-66, *Environmental testing – Part 2: Test methods – Test Cx: Damp heat, steady state (unsaturated pressurized vapour)*

IEC 60068-2-67, *Environmental testing – Part 2: Tests – Test Cy: Damp heat, steady state, accelerated test primarily intended for components*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IPC-TM-650 No.2.6.14.1, *Electrochemical Migration Resistance Test [viewed 2017-01-31]. Available at: https://www.ipc.org/TM/2-6_2-6-14-1.pdf*

IPC-TM-650 No.2.6.25, *Conductive Anodic Filament (CAF) Resistance Test: X-Y Axis [viewed 2017-01-31]. Available at: https://www.ipc.org/4.0_Knowledge/4.1_Standards/test/2-6-25.pdf*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60068-1 as well as the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses: